

Product Specification

CUSTOMER: _____

DESCRIPTION: _____

RF TRANSFORMER

MNC P/N: _____

RFT-131SG

REVISION: _____

X0

CUSTOMER P/N: _____

ISSUED DATE: _____

2016-10-08

PHOTO OF
PRODUCT: _____

WEIGHT: _____

0.085g

PREPARED BY	CHECKED BY	APPROVED BY
Wen Lee	Sonny Zhang	Simon Zhang

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CHANGE RECORD

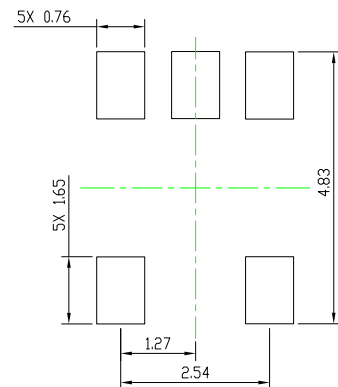
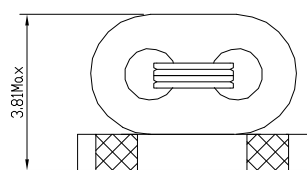
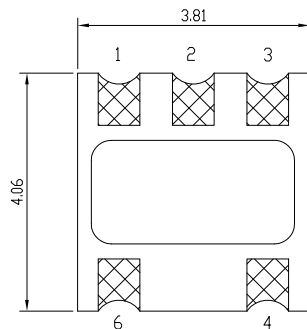
REV.	DESCRIPTION (Content or Reason For Change)	DATE	REVISER
X0	INITIAL RELEASE	2016-10-08	Wen Lee

- RF Transformer
- Impedance=50Ω
- Operating temperature range: -20℃ to +85℃
- Storage temperature range: -55℃ to +100℃
- RoHS compliant

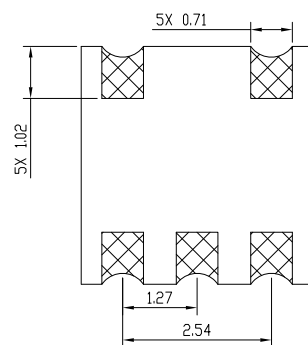
Electrical Specifications @25°C,Z ₀ =50Ω						
Part Number	Ω Ratio	Insertion Loss			DC Current	RF Power
	Sec: Pri(1-3:6-4)	1.5-600MHz	2-400MHz	3-350MHz		
RFT-131SG	4:1	3.0dB	2.0dB	1.0dB	30mA	0.25W
						1.5-600MHz

Note: Insertion Loss is referenced to mid-band loss, 0.6dB typ.

MECHANICAL DIMENSIONS(units:mm)

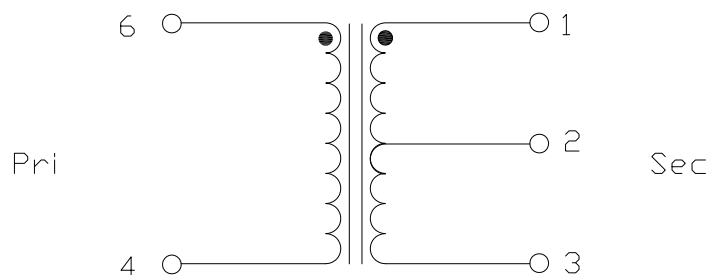


Recommended PAD Layout



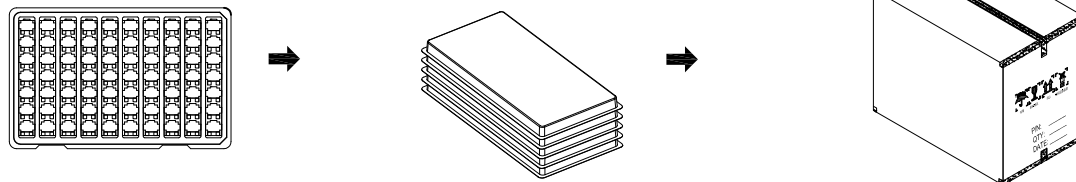
Unless otherwise specified all tolerances are: ±0.25 mm

SCHEMATIC



PACKING:

☐ Tray:

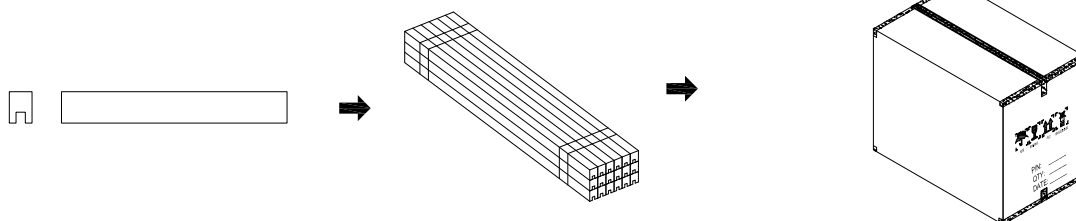


Q'ty

_____ PCS Per Tray

_____ PCS Per Carton

☐ Tube:

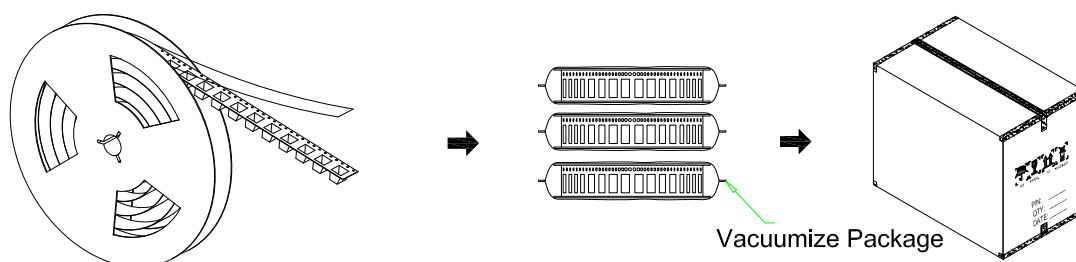


Q'ty

_____ PCS Per Tube

_____ PCS Per Carton

☒ Reel:



Q'ty

2500 PCS Per Reel

30000 PCS Per Carton

MOISTURE SENSITIVE LEVEL:

1. Level:1

2.Shelf Life:Unlimited

3.Storage Condition:<=30℃/85% RH

RECOMMENDED SOLDERING PROFILE:

☒ 1. Reflow soldering profile(According to IPC/JEDEC J-STD-020C)

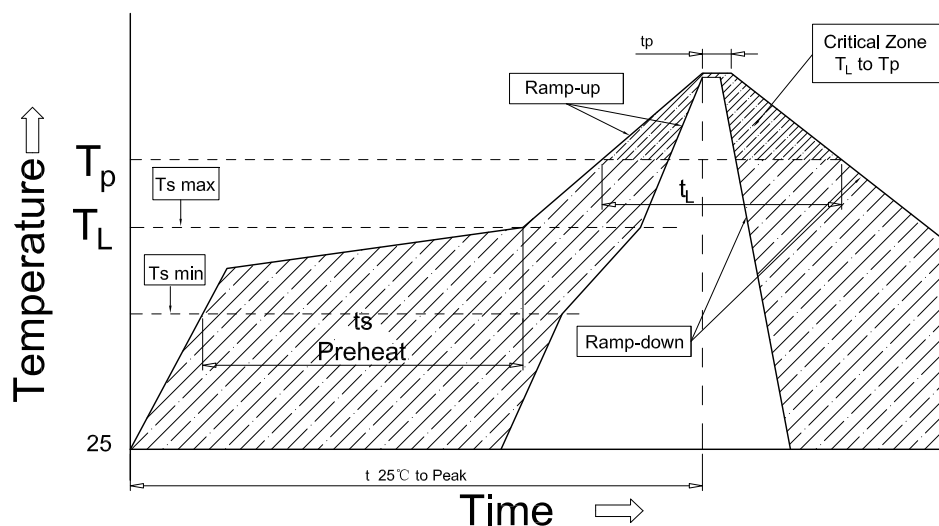


Table 1-1 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3°C/second max	3°C/second max
Preheat		
-Temperature Min (T _{smin})	100°C	150°C
-Temperature Max (T _{smax})	150°C	200°C
-Time (t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
-Time (t _L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature(T _p)	See IPC/JEDEC J-STD-020C Table 4-1	See IPC/JEDEC J-STD-020C Table 4-2
Time within 5°C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max	8 minutes max

Note1: All temperatures refer to topside of the package, measured on the package body surface

- Suggested soldering process: Reflow soldering
- Solder Paste: Sn96.5Ag3.0Cu0.5
- Silkscreen thickness: 0.15mm Min.

☐ 2. Wave soldering profile

